

Precision Reference

FEATURES

- Available at 2.5V, 4.5V, 5V, and 10V
- Plug-In Replacement for Present References
- Ultra-Low Drift: 3ppm/°C Typical
- Curvature Corrected
- Series or Shunt Operation
- Ultra-High Line Rejection: ≈0.5ppm/V
- Low Output Impedance: ≈ 0.02Ω
- Tight Initial Output Voltage: < 0.05%
- Can Be Heated for Drifts Below 2ppm/°C
- 100% Noise Tested
- Temperature Output

APPLICATIONS

- A/D and D/A Converters
- Precision Regulators
- Constant Current Sources
- V/F Converters
- Bridge Excitation

DESCRIPTION

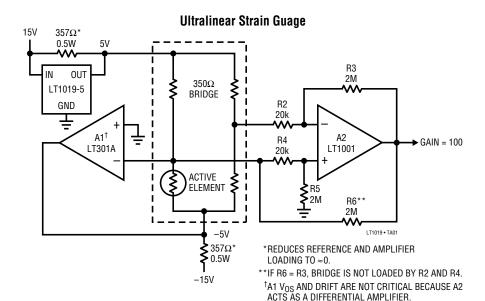
The LT1019 is a third generation bandgap voltage reference utilizing thin film technology and a greatly improved curvature correction technique. Wafer level trimming of both reference and output voltage combines to produce units with high yields to very low TC and tight initial tolerance of output voltage.

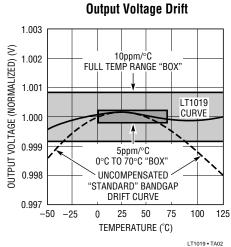
The LT1019 can both sink and source up to 10mA and can be used in either the series or shunt mode. This allows the reference to be used for both positive and negative output voltages without external components. Minimum input/output voltage is less than 1V in the series mode, providing improved tolerance of low line conditions.

The LT1019 is available in four voltages: 2.5V, 4.5V, 5V, and 10V. It is a direct replacement for most bandgap references presently available including AD580, AD581, REF-01, REF-02, MC1400, MC1404, and LM168.

For ultra-low drift applications (<2ppm/°C), the LT1019 can be operated in a heated mode by driving an internal resistor with an external amplifier. Chip temperature can be externally set for minimum power consumption.

TYPICAL APPLICATION



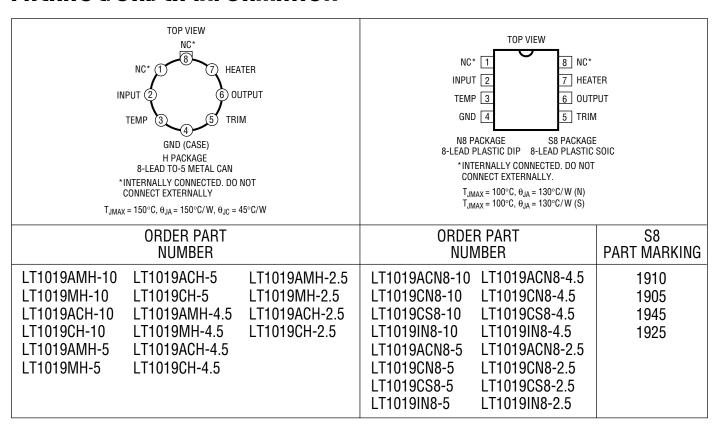


ABSOLUTE MAXIMUM RATINGS

Input Voltage	40V
Output Voltage (Note 1)	
LT1019-5, LT1019-10	16V
LT1019-2.5, LT1019-4.5	. 7V
Output Short-Circuit Duration (Note 1)	
V _{IN} < 20V Inde	finite
$20V \le V_{IN} \le 35V$) sec

Trim Pin Voltage ±30V
Temp Pin Voltage 5V
Heater Voltage
Continuous 18V
Intermittent (30 sec)
Storage Temperature Range65°C to 150°C
Lead Temperature (Soldering, 10 sec) 300°C

PACKAGE/ORDER INFORMATION



ELECTRICAL CHARACTERISTICS $V_{IN} = 15V$, $I_{OUT} = 0$, $T_J = 25^{\circ}C$, unless otherwise noted.

SYMBOL					LT1019A		LT1019			T
	PARAMETER	CONDITIONS			TYP MAX		MIN	TYP	MAX	UNITS
	Output Voltage Tolerance				0.002	0.05		0.02	0.2	%
TC	Output Voltage Temperature Coefficient (Note 2)	LT1019C (0°C to 70°C) LT1019M (-55°C to 125°C) LT1019I (-40°C to 85°C)	•		3 5	5 10		5 8 5	20 25 20	ppm/°C ppm/°C ppm/°C
$\frac{\Delta V_{OUT}}{\Delta V_{IN}}$	Line Regulation (Note 3)	$(V_{OUT} + 1.5V) \le V_{IN} \le 40V$	•		0.5 1.0	3 5		0.5 1.0	3 5	ppm/V ppm/V
RR	Ripple Rejection	50Hz ≤ f ≤ 400Hz	•	90 84	110		90 84	110		dB dB

ELECTRICAL CHARACTERISTICS $V_{IN} = 15V$, $I_{OUT} = 0$, $T_J = 25^{\circ}C$, unless otherwise noted.

-				LTC1019A				LTC1019		
SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	MIN	TYP	MAX	UNITS
ΔV_{OUT}	Load Regulation Series	$0 \le I_{OUT} \le 10 \text{mA}^*$			0.02	0.05		0.02	0.05	mV/mA (Ω)
ΔI_{OUT}	Mode (Notes 3, 4)		•			0.08			0.08	mV/mA (Ω)
	Load Regulation,	$1 \text{mA} \le I_{\text{SHUNT}} \le 10 \text{mA} \text{ (Notes 4, 5)}$								
	Shunt Mode	2.5V, 4.5V, 5V	•		0.1	0.4		0.1	0.4	mV/mA (Ω)
		10V	•			8.0			8.0	mV/mA (Ω)
	Thermal Regulation (Note 6)	$\Delta P = 200 \text{mW}, t = 50 \text{ms}$			0.1	0.5		0.1	0.5	ppm/mW
IQ	Quiescent Current				0.65	1.0		0.65	1.2	mA
	Series Mode		•			1.3			1.5	mA
	Minimum Shunt Current	(Note 7)	•		0.5	0.8		0.5	0.8	mA
	Minimum Input/Output	I _{OUT} ≤ 1mA	•		0.9	1.1		0.9	1.1	V
	Voltage Differential	I _{OUT} = 10mA	•			1.3			1.3	V
	Trim Range	LT1019-2.5		±3.5	±6		±3.5	±6		%
		LT1019-5		±3.5	5, -13		±3.5	5, -13		%
		LT1019-10		±3.5	5, -27		±3.5	5, -27		%
	Heater Resistance			300	400	500	300	400	500	Ω
I _{SC}	Short-Circuit Current	$2V \le V_{IN} \le 35V$		15	25	50	15	25	50	mA
	Output Connected to GND		•	10			10			mA
e _n	Output Voltage Noise	$10Hz \le f \le 1kHz$			2.5	4		2.5	4	ppm (RMS)
	(Note 9)	$0.1Hz \le f \le 10Hz$			2.5			2.5		ppm (P-P)

The ● denotes specifications which apply over the full operating temperature range.

Note 1: These are high power conditions and are therefore guaranteed only at temperatures equal to or below 70°C. Input is either floating, tied to output, or held higher than output.

Note 2: Output voltage drift is measured using the box method. Output voltage is recorded at T_{MIN} , 25°C, and T_{MAX} . The lowest of these three readings is subtracted from the highest and the resultant difference is divided by $(T_{MAX} - T_{MIN})$.

Note 3: Line regulation and load regulation are measured on a pulse basis with low duty cycle. Effects due to die heating must be taken into account separately. See thermal regulation and application section.

Note 4: Load regulation is measured at a point 1/8" below the base of the package with Kelvin contacts.

Note 5: Shunt regulation is measured with the input floating. This parameter is also guaranteed with the input connected $(V_{IN}-V_{OUT})>1V$, $0mA \leq I_{SINK} \leq 10mA$. Shunt and sink current flow into the output.

Note 6: Thermal regulation is caused by die temperature gradients created by load current or input voltage changes. This effect must be added to normal line or load regulation.

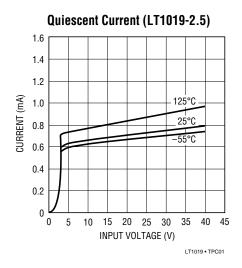
Note 7: Minimum shunt current is measured with shunt voltage held 20mV below the value measured at 1mA shunt current.

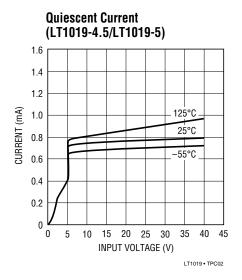
Note 8: Minimum input/output voltage is measured by holding input voltage 0.5V above the nominal output voltage, while measuring $V_{IN}-V_{OUT}$.

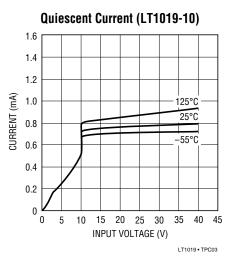
Note 9: RMS noise is measured with a single highpass filter at 10Hz and a 2-pole lowpass filter at 1kHz. The resulting output is full-wave rectified and then integrated for a fixed period, making the final reading an average as opposed to RMS. A correction factor of 1.1 is used to convert from average to RMS, and a second correction of 0.88 is used to correct the non-ideal bandpass of the filters.

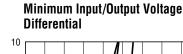


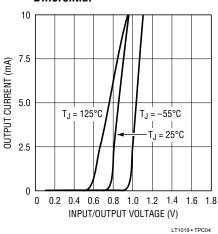
TYPICAL PERFORMANCE CHARACTERISTICS

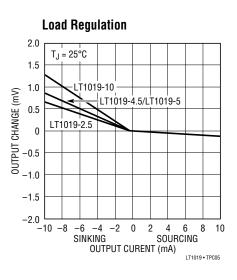


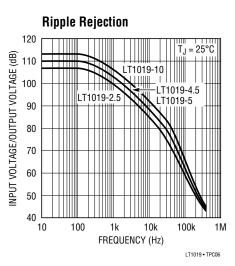




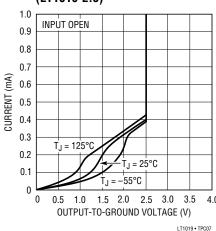




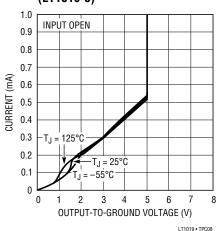




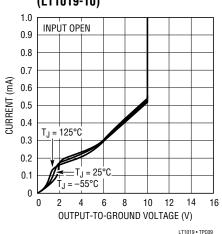
Shunt Mode Characteristics (LT1019-2.5)





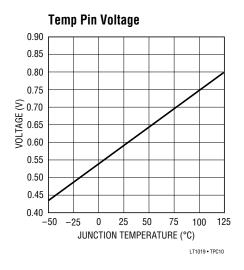


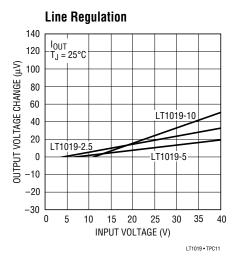
Shunt Mode Characteristics (LT1019-10)

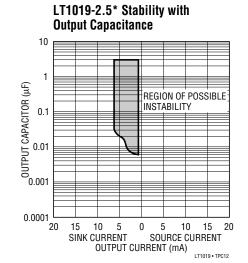




TYPICAL PERFORMANCE CHARACTERISTICS

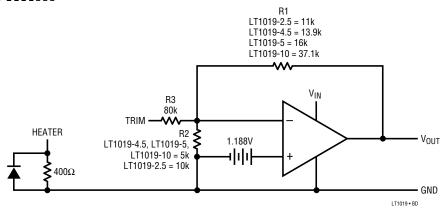






* LT1019-4.5/LT1019-5/LT1019-10 ARE STABLE WITH ALL LOAD CAPACITANCE.

BLOCK DIAGRAM



APPLICATIONS INFORMATION

Line and Load Regulation

Line regulation on the LT1019 is nearly perfect. A 10V change in input voltage causes a typical output shift of less than 5ppm. Load regulation (sourcing current) is nearly as good. A 5mA change in load current shifts output voltage by only $100\mu V$. These are *electrical* effects, measured with low duty cycle pulses to eliminate heating effects. In real world applications, the *thermal* effects of load and line changes must be considered.

Two separate thermal effects are evident in monolithic circuits. One is a gradient effect, where power dissipation on the die creates temperature gradients. These gradients can cause output voltage shifts even if the overall temperature coefficient of the reference is zero. The LT1019, unlike previous references, specifies thermal regulation caused by die temperature gradients. The specification is 0.5 ppm/mW. To calculate the effect on output voltage, simply multiply the *change* in device power dissipation by the



APPLICATIONS INFORMATION

thermal regulation specification. Example: a 10V device with a nominal input voltage of 15V and load current of 5mA. Find the effect of an input voltage change of 1V and a load current change of 2mA.

```
\Delta P (line change) = (\Delta V_{IN})(I_{LOAD}) = (1V)(5mA) = 5mA
\Delta V_{OUT} = (0.5ppm/mW)(5mW) = 2.5ppm
\Delta P (load change) = (\Delta I_{LOAD})(V_{IN} - V_{OUT})
= (2mA)(5V) = 10mW
\Delta V_{OUT} = (0.5ppm/mW)(10mW) = 5ppm
Even though those effects are small, they should be taken
```

Even though these effects are small, they should be taken into account in critical applications, especially where input voltage or load current is high.

The second thermal effect is overall die temperature change. The magnitude of this change is the product of change in power dissipation times the thermal resistance (θ_{JA}) of the IC package $\cong (100^{\circ}\text{C/W}-150^{\circ}\text{C/W}).$ The effect on reference output is calculated by multiplying die temperature change by the temperature drift specification of the reference. Example: same conditions as above with $\theta_{JA}=150^{\circ}\text{C/W}$ and an LT1019 with 20ppm/°C drift specification.

```
\Delta P (line change) = 5mW

\Delta V_{OUT} = (5mW)(150^{\circ}C/W)(20ppm/^{\circ}C)

= 15ppm

\Delta P (load change) = 10mW

\Delta V_{OUT} = (10mW)(150^{\circ}C/W)(20ppm/^{\circ}C)

= 30ppm
```

These calculations show that thermally induced output voltage variations can easily exceed the electrical effects. In critical applications where shifts in power dissipation are expected, a small clip-on heat sink can significantly improve these effects by reducing overall die temperature change. Alternately, an LT1019A can be used with four times lower TC. If warm-up drift is of concern, these measures will also help. With warm-up drift, *total* device power dissipation must be considered. In the example given, warm-up drift (worst case) is equal to:

```
Warm-up drift = [(V_{IN})(I_Q) + (V_{IN} - V_{OUT})(I_{LOAD})]

[(\theta_{JA})(TC)]

with IQ (quiescent current) = 0.6mA,

Warm-up drift = [(15V)(0.6mA) + (5V)(5mA)]

[(150^{\circ}C/W)(25ppm/^{\circ}C)]

= 127.5ppm
```

Note that 74% of the warm-up drift is due to load current times input/output differential. This emphasizes the importance of keeping both these numbers low in critical applications. With heavy loads, warm-up drift can also be improved using the technique described under "Driving Loads Above 10mA" or by heat sinking.

Note that line regulation is now affected by reference output impedance. R1 should have a wattage rating high enough to withstand full input voltage if output shorts must be tolerated. Even with load currents below 10mA, R1 can be used to reduce power dissipation in the LT1019 for lower warm-up drift, etc.

Output Trimming

Output voltage trimming on the LT1019 is nominally accomplished with a potentiometer connected from output to ground with the wiper tied to the trim pin. The LT1019 was made compatible with existing references, so the trim range is large: +6%, -6% for the LT1019-2.5, +5%, -13% for the LT1019-5, and +5%, -27% for the LT1019-10. This large trim range makes precision trimming rather difficult. One solution is to insert resistors in series with both ends of the potentiometer. This has the disadvantage of potentially poor tracking between the fixed resistors and the potentiometer. A second method of reducing trim range is to insert a resistor in series with the wiper of the potentiometer. This works well only for very small trim range because of the mismatch in TCs between the series resistor and the internal thin film resistors. These film resistors can have a TC as high as 500ppm/°C. That same TC is then transferred to the change in output voltage: a 1% shift in output voltage causes a $(500ppm)(1\%) = 5ppm/^{\circ}C$ change in output voltage drift.

APPLICATIONS INFORMATION

The worst case error in initial output voltage for the LT1019 is 0.2%, so a series resistor is satisfactory if the output is simply trimmed to nominal value. The maximum TC shift expected would be 1ppm/°C.

Using the Temp Pin

The LT1019 has a TEMP pin like several other bandgap references. The voltage on this pin is directly proportional to absolute temperature (PTAT) with a slope of $\approx 2.1 \text{mV/°C}$. Room temperature voltage is therefore $\approx (295^{\circ}\text{K})(2.1 \text{mV/°C}) = 620 \text{mV}$. Previous bandgap references have been very sensitive to any loading on the TEMP pin because it is an integral part of the reference "core" itself. The LT1019 "taps" the core at a special point which has much less effect on the reference. The relationship between TEMP pin loading and a change in reference output voltage is less than $0.05\%/\mu\text{A}$, about ten times improvement over previous references.

Output Bypassing

The LT1019 is designed to be stable with a wide range of load currents and output capacitors. The 4.5V, 5V, and 10V devices do not oscillate under any combination of capacitance and load. The 2.5V device can oscillate when sinking currents between 1mA and 6mA for load capacitance between 400pF and 2μ F (see Figure 1).

If output bypassing is desired to reduce high frequency output impedance, keep in mind that loop phase margin is significantly reduced for output capacitors between 500pF and $1\mu F$ if the capacitor has low ESR (Effective Series Resistance). This can make the output "ring" with transient loads. The best transient load response is obtained by deliberately adding a resistor to increase ESR as shown in Figure 1.

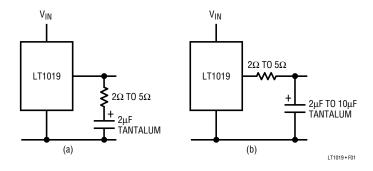
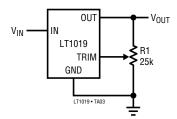


Figure 1. Output Bypassing

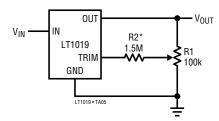
Use configuration (a) if DC voltage error cannot be compromised as load current changes. Use (b) if absolute minimum peak perturbation at the load is needed. For best transient response, the output can be loaded with ≥ 1 mA DC current.

TYPICAL APPLICATIONS

Wide Range Trim $\geq \pm 5\%$



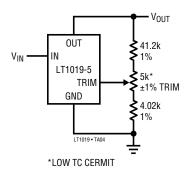
Narrow Trim Range ($\pm 0.2\%$)



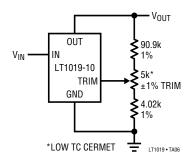
*INCREASE TO 4.7M FOR LT1019A (±0.05%)

TYPICAL APPLICATIONS

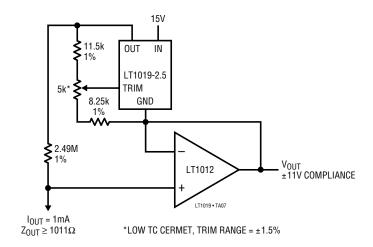
Trimming LT1019-5 Output to 5.120V



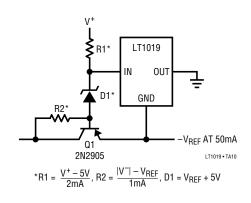
Trimming LT1019-10 Output to 10.240V



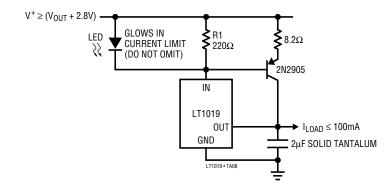
Precision 1µA Current Source



Negative Series Reference

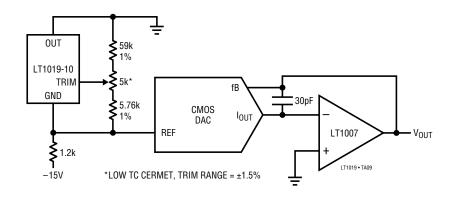


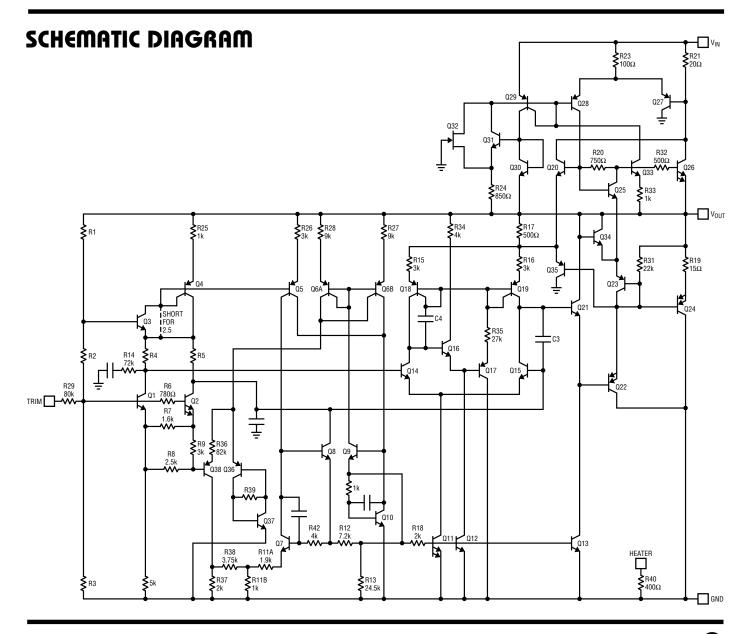
Output Current Boost with Current Limit



TYPICAL APPLICATIONS

Negative 10V Reference for CMOS DAC

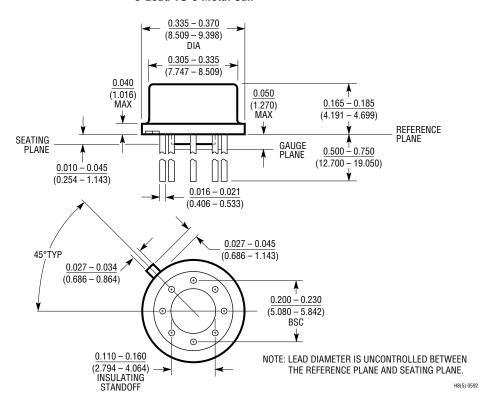




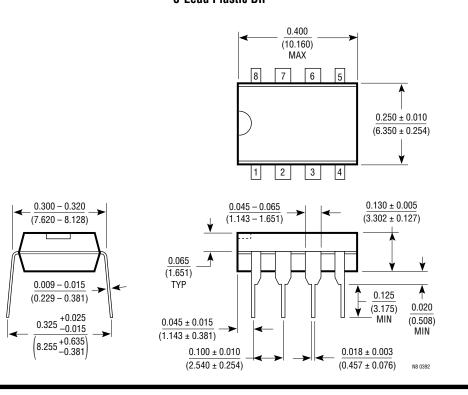


PACKAGE DESCRIPTION Dimensions in inches (millimeters) unless otherwise noted.

H Package 8-Lead TO-5 Metal Can

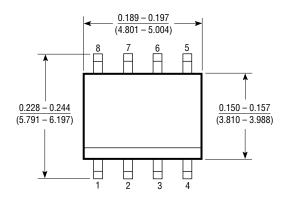


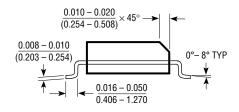
H8 Package 8-Lead Plastic DIP

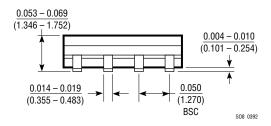


PACKAGE DESCRIPTION Dimensions in inches (millimeters) unless otherwise noted.

S8 Package 8-Lead Plastic SOIC







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